SN74CBTLV3245A-Q1 Low-Voltage Octal FET Bus Switch

1 Features

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results: –
  - Device Temperature Grade 1: –40°C to +125°C
  - Ambient Operating Temperature Range
  - Device HBM ESD Classification Level 2
  - Device CDM ESD Classification Level C5
- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)

2 Applications

- Analog and digital multiplexing and demultiplexing
- Diagnostics and monitoring
- Zonal Architecture
- Body control modules
- Battery management systems (BMS)
- HVAC control module
- ADAS
- On-board (OBC) and wireless charging
- Automotive head unit
- Telematics

3 Description

The SN74CBTLV3245A-Q1 provides eight bits of high-speed bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When output enable ($\overline{OE}$) is low, the 8-bit bus switch is on, and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and the high-impedance state exists between the two ports.

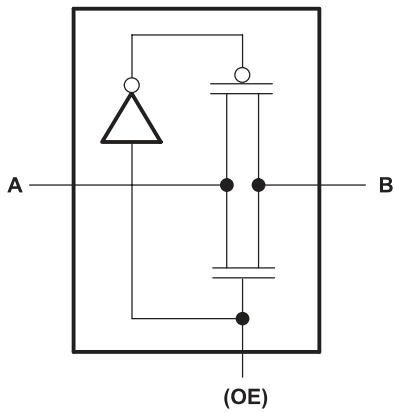
This device is fully specified for partial-power-down applications using I_{off}. The I_{off} feature maitains that damaging current does not backflow through the device when the device is powered down. The device has isolation during power off.

To maintain the high-impedance state during power up or power down, $\overline{OE}$ is tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Package Information

PART NUMBER	PACKAGE (1)	PACKAGE SIZE(2)
74CBTLV3245APWRQ1	TSSOP (20)	6.50mm × 4.40mm
74CBTLV3245ADGSRQ1	VSSOP (20)	5.10mm × 3.00mm
74CBTLV3245ARKSRQ1	VQFN (20)	4.50mm × 2.50mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.
(2) The package size (length x width) is a nominal value and includes pins, where applicable.



Simplified Schematic (Each FET Switch)

Table of Contents

4 Pin Configuration and Functions

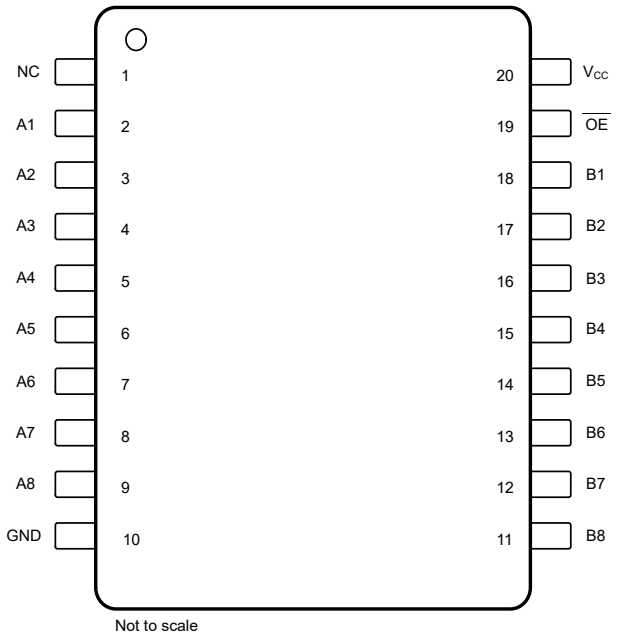


Figure 4-1. DGS, and PW Package 20-Pin VSSOP, and TSSOP (Top View)

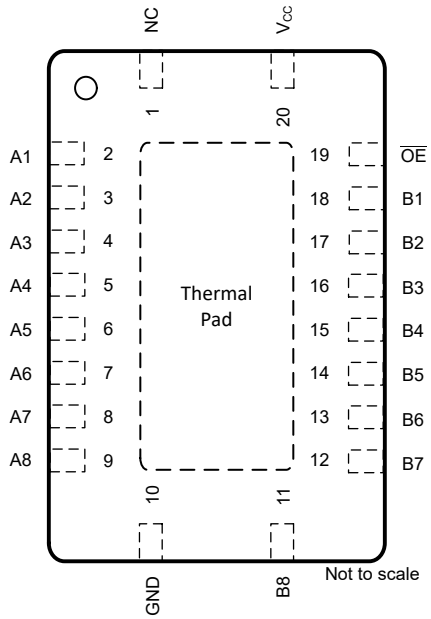


Figure 4-2. RKS Package 20-Pin VQFN (Top View)

Table 4-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
NC	1	I/O	No internal connection. Can be shorted to GND or left floating
A1	2	I/O	Input/output pin
A2	3	I/O	Input/output pin
A3	4	I/O	Input/output pin
A4	5	I/O	Input/output pin
A5	6	I/O	Input/output pin
A6	7	I/O	Input/output pin
A7	8	I/O	Input/output pin
A8	9	I/O	Input/output pin
GND	10	GND	Ground pin
B8	11	I/O	Input/output pin
B7	12	I/O	Input/output pin
B6	13	I/O	Input/output pin
B5	14	I/O	Input/output pin
B4	15	I/O	Input/output pin
B3	16	I/O	Input/output pin
B2	17	I/O	Input/output pin
B1	18	I/O	Input/output pin

Table 4-1. Pin Functions (continued)

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
$\overline{OE}$	19	I	Output Enable, active low
V_{CC}	20	PWR	Voltage Supply pin

1. I = Input, O = Output, PWR = Power

Table 4-2. Function Table

INPUTS	FUNCTION
$\overline{OE}$	
L	A port = B port
H	Disconnect

4.1 Pin Functions

Table 4-3. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
NC	1	I/O	No internal connection. Can be shorted to GND or left floating
A1	2	I/O	Input/output pin
A2	3	I/O	Input/output pin
A3	4	I/O	Input/output pin
A4	5	I/O	Input/output pin
A5	6	I/O	Input/output pin
A6	7	I/O	Input/output pin
A7	8	I/O	Input/output pin
A8	9	I/O	Input/output pin
GND	10	GND	Ground pin
B8	11	I/O	Input/output pin
B7	12	I/O	Input/output pin
B6	13	I/O	Input/output pin
B5	14	I/O	Input/output pin
B4	15	I/O	Input/output pin
B3	16	I/O	Input/output pin
B2	17	I/O	Input/output pin
B1	18	I/O	Input/output pin
$\overline{OE}$	19	I	Output Enable, active low
V_{CC}	20	PWR	Voltage Supply pin

Table 4-4. Function Table

INPUTS	FUNCTION
$\overline{OE}$	
L	A port = B port
H	Disconnect

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	4.6	V
V_I	Input voltage range(2)		–0.5	4.6	V
	Continuous channel current			128	mA
I_{IK}	Input clamp current	$V_{I/O} < 0$		–50	mA
T_{stg}	Storage temperature range		-65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

5.3 Thermal Information

THERMAL METRIC[1]		SN74CBTLV3245A-Q1			UNIT
		PW(TSSOP)	RKS(VQFN)	DGS(VSSOP)	
		20 Pins	20 Pins	20 Pins	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	105.9	71.88	120.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	49.3	45.07	62.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	67.6	17.91	75.3	°C/W
ψ_{JT}	Junction-to-top characterization parameter	8.5	45.03	8.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	67.0	76.32	74.7	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	28.51	N/A	°C/W

5.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
V_{IH}	High-level control input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level control input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
		V_{CC} = 2.7 V to 3.6 V		0.8	
T_A	Operating free-air temperature		–40	125	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP(1)	MAX	UNIT
V_{IK}	Control inputs	V_{CC} = 3 V,	I_I = –18 mA				–1.2	V
	Data inputs						–0.8	
I_I		V_{CC} = 3.6 V,	V_I = V_{CC} or GND				±60	µA
I_{off}		V_{CC} = 0,	V_I or V_O = 0 to 3.6 V				40	µA
I_{CC}		V_{CC} = 3.6 V,	I_O = 0,	V_I = V_{CC} or GND			20	µA
ΔI_{CC} (2)	Control inputs	V_{CC} = 3.6 V,	One input at 3 V,	Other inputs at V_{CC} or GND			300	µA
C_i	Control inputs	V_I = 3 V or 0				4		pF
$C_{io(OFF)}$		V_O = 3 V or 0,	$\overline{OE}$ = V_{CC}			9		pF
r_{on} (3)		V_{CC} = 2.3 V, TYP at V_{CC} = 2.5 V	V_I = 0	I_O = 64 mA		5	8	Ω
				I_O = 24 mA		5	8	
			V_I = 1.7 V,	I_O = 15 mA		27	40	
		V_{CC} = 3 V	V_I = 0	I_O = 64 mA		5	7	
				I_O = 24 mA		5	7	
			V_I = 2.4 V,	I_O = 15 mA		10	15	

(1) All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.
(2) This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.
(3) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

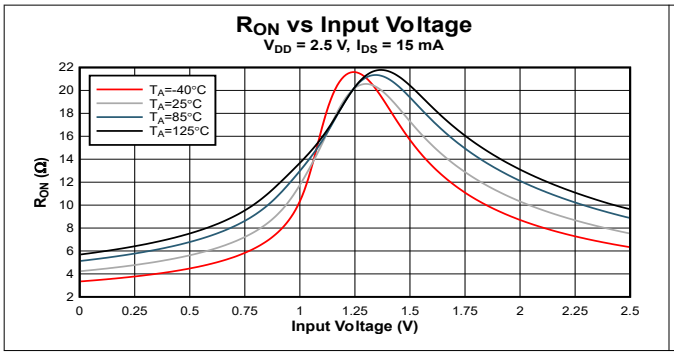
5.6 Switching Characteristics

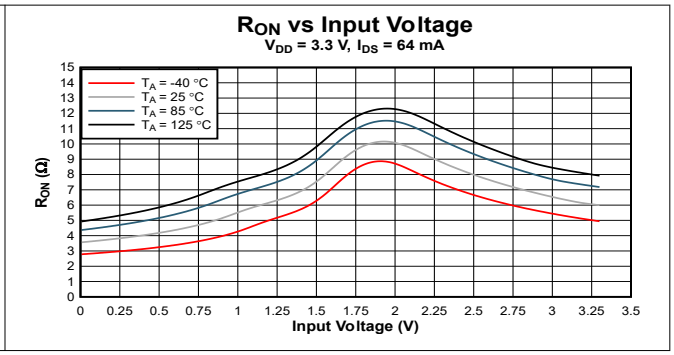
over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t_{pd} (1)	A or B	B or A		0.15		0.25	ns
t_{en}	$\overline{OE}$	A or B	1	6	1	4.7	ns
t_{dis}	$\overline{OE}$	A or B	1	6.1	1	6.4	ns

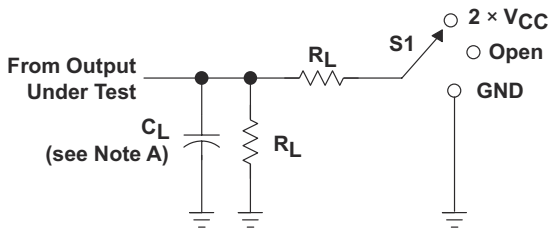
(1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

5.7 Typical Characteristics





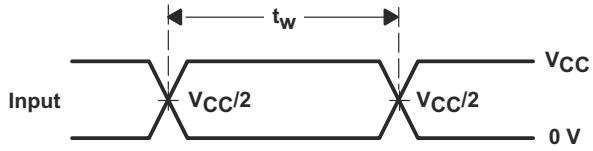
6 Parameter Measurement Information



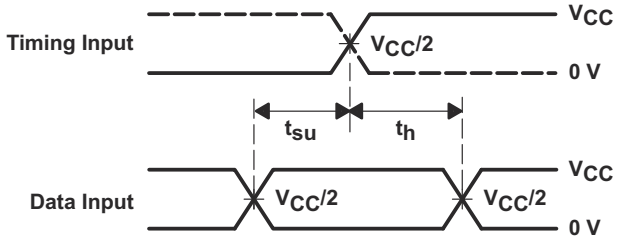
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 × V_{CC} GND

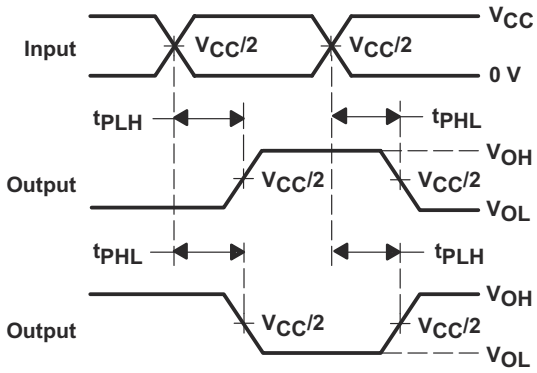
V_{CC}	C_L	R_L	V_Δ
2.5 V ± 0.2 V	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	50 pF	500 Ω	0.3 V



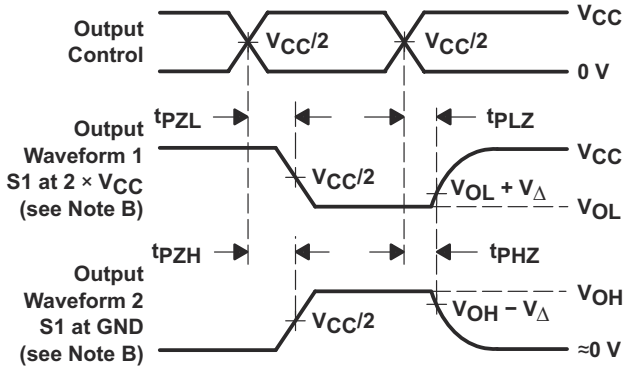
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2 ns, t_f ≤ 2 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74CBTLV3245A-Q1 provides eight bits of high-speed bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When output enable ($\overline{OE}$) is low, the 8-bit bus switch is on, and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and the high-impedance state exists between the two ports.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} feature maitains that damaging current does not backflow through the device when the device is powered down. The device has isolation during power off.

To maintain the high-impedance state during power up or power down, $\overline{OE}$ is tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.2 Functional Block Diagram

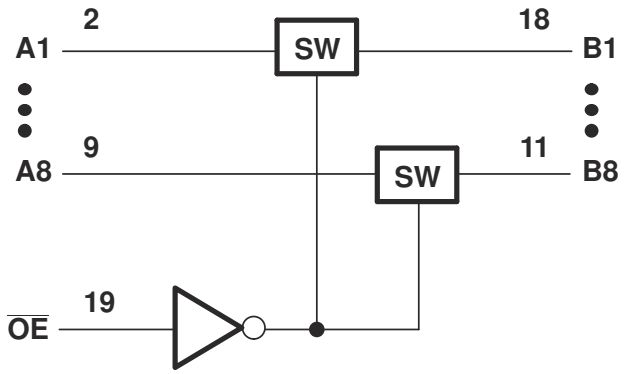


Figure 7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

The SN74CBTLV3245A-Q1 features 5-Ω switch connection between ports, allowing for low signal loss across the switch. Rail-to-rail switching on data I/O allows for full voltage swing outputs. I_{off} supports partial-power-down mode operation, protecting the chip from voltages at output ports when it is not powered on. Latch-up performance exceeds 100 mA per JESD 78, Class II.

7.4 Device Functional Modes

Table 7-1 lists the functional modes of the SN74CBTLV3245A-Q1.

Table 7-1. Function Table

INPUT $\overline{OE}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The SN74CBTLV3245A-Q1 can be used to switch a signal path. The switch is bidirectional, so the A and B pins can be used as either inputs or outputs. This switch is typically used when there is one signal path that needs to be isolated at certain times.

8.2 Typical Application

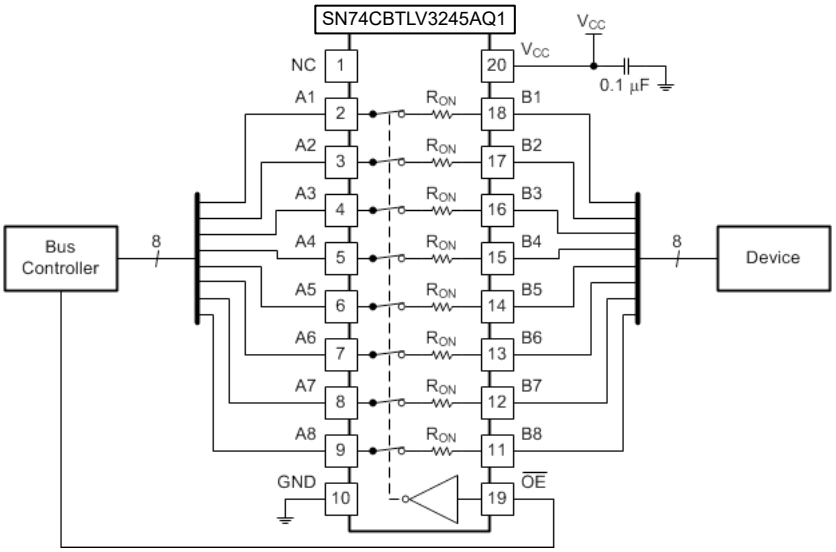


Figure 8-1. Typical Application Schematic

8.2.1 Design Requirements

The SN74CBTLV3245A-Q1 device can be properly operated without any external components. TI recommends pulling up the digital control pin (OE) to VCC or pulling down to GND to avoid undesired switch positions that can result from the floating pin. A floating digital pin can cause excess current consumption refer to Implications of Slow or Floating CMOS Inputs.

8.2.2 Detailed Design Procedure

When $\overline{OE}$ is high, the active bus. This means that there is a low impedance path between the A and B pins. The 0.1-µF capacitor on VCC is a decoupling capacitor and is placed as close as possible to the device.

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating listed in the Section 5.4 table.

Each V_{CC} terminal has a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1µF bypass capacitor is recommended. If multiple pins are labeled V_{CC}, then a 0.01µF or 0.022µF capacitor is recommended for each V_{CC} because the V_{CC} pins are tied together internally. For devices with dual-supply pins operating at different voltages, for example V_{CC} and V_{DD}, a 0.1µF bypass capacitor is recommended for each supply pin. To reject different frequencies of noise, use multiple bypass capacitors in parallel. Capacitors with values of 0.1µF and 1µF are commonly used in parallel. The bypass capacitor is installed as close to the power terminal as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

Reflections and matching are closely related to the loop antenna theory but are different enough to be discussed separately from the theory. When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self–inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. Figure 8-2 shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

8.4.2 Layout Example

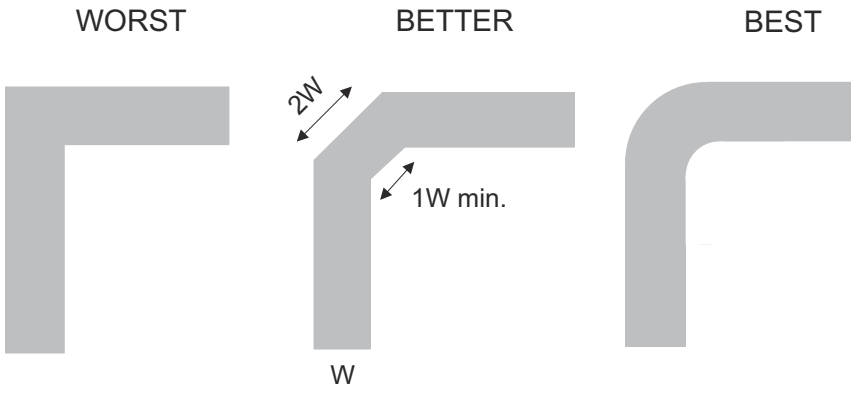


Figure 8-2. Trace Example

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *Implications of Slow or Floating CMOS Inputs*
- Texas Instruments, *Selecting the Right Texas Instruments Signal Switch*

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
January 2026	*	Initial Release

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

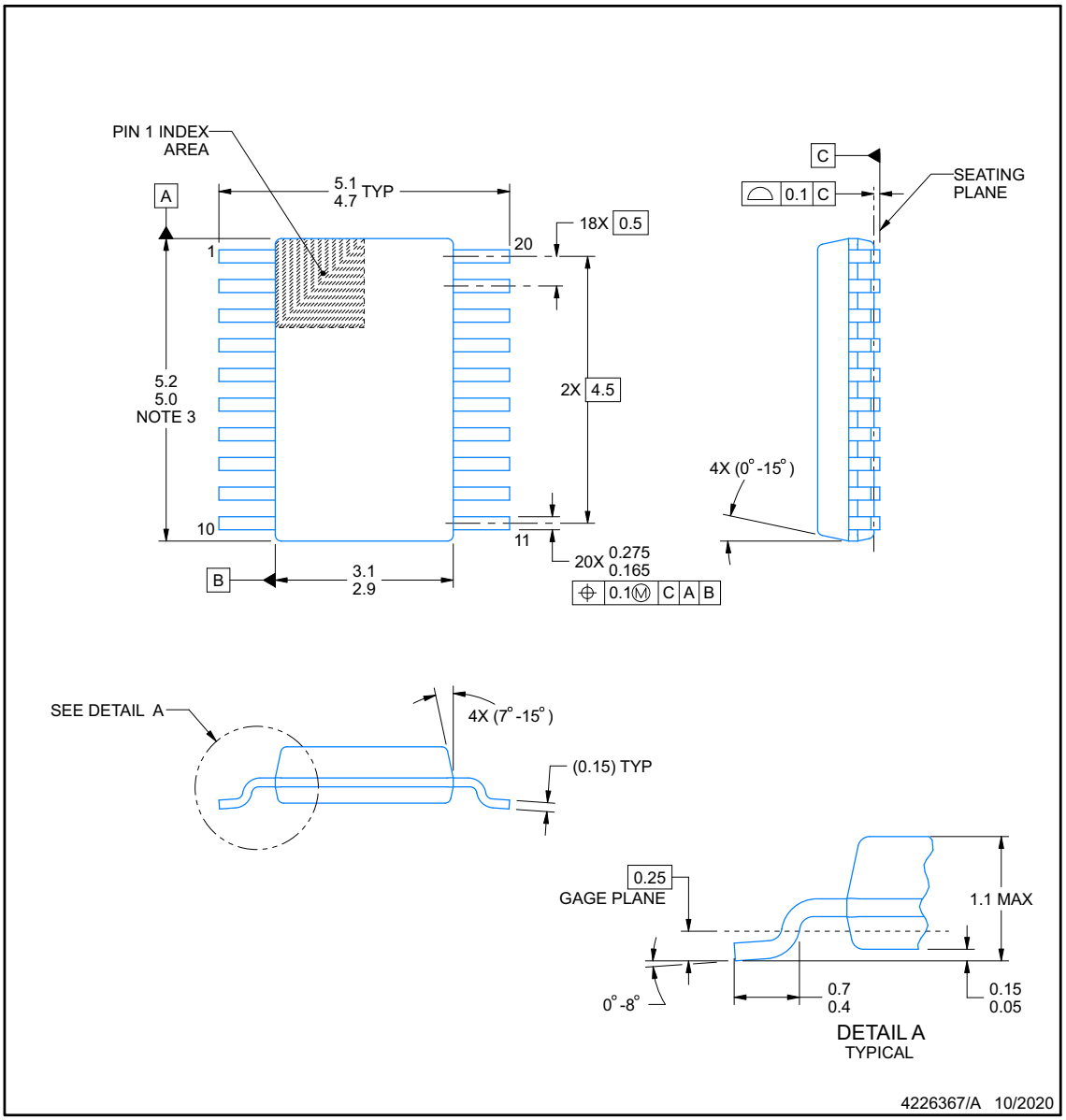
11.1 Mechanical Data

DGS0020A

PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



PowerPAD is a trademark of Texas Instruments.

NOTES:

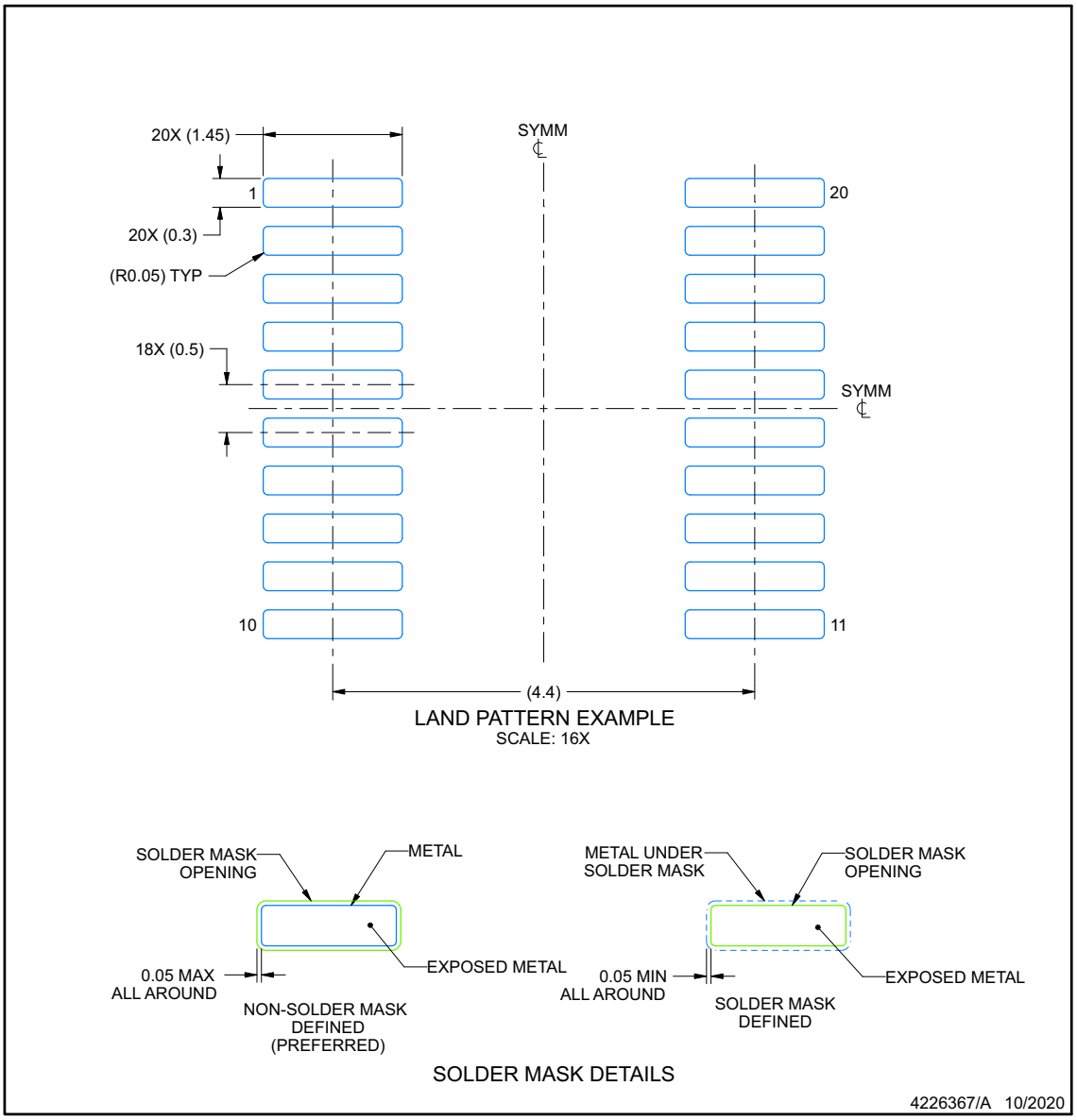
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

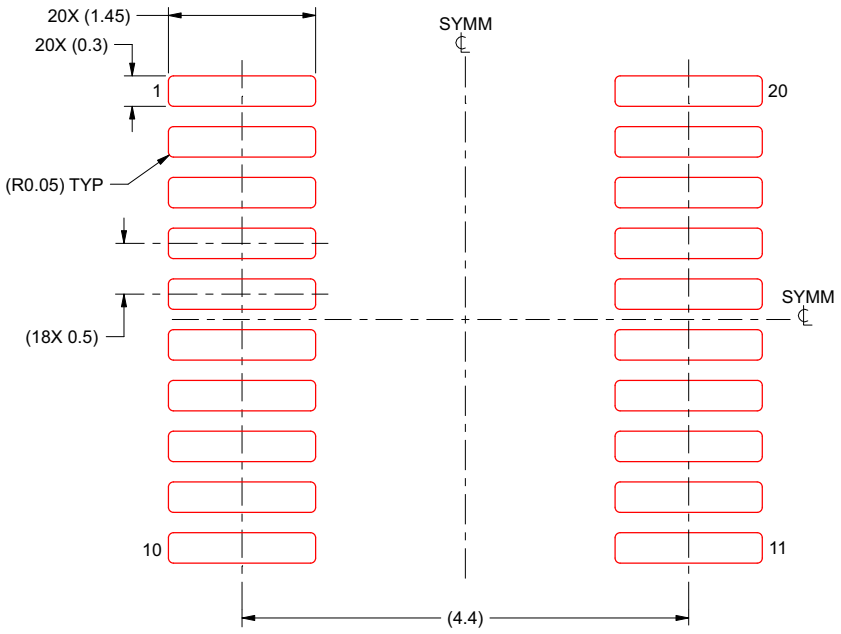
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

4226367/A 10/2020

NOTES: (continued)

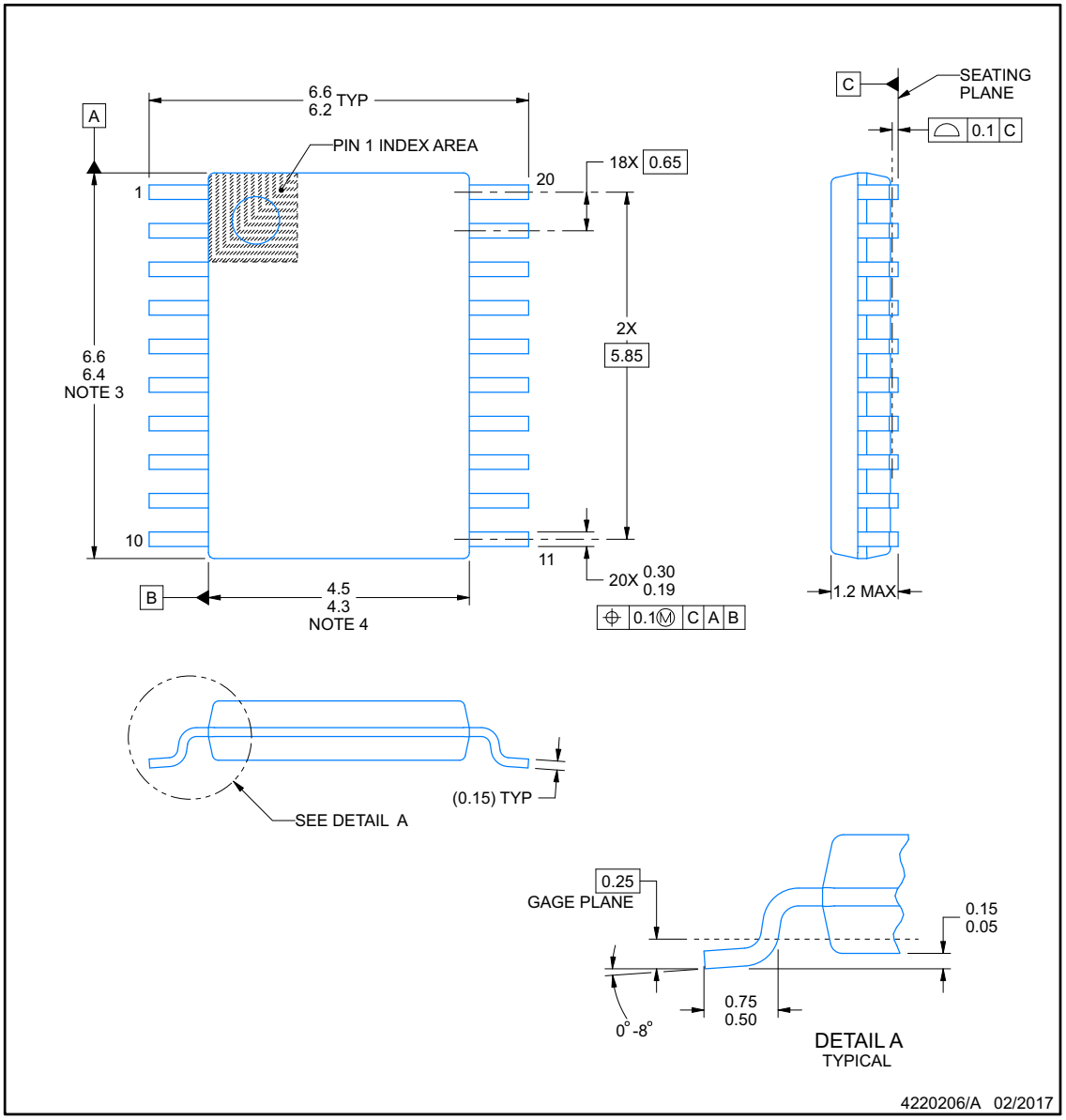
11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

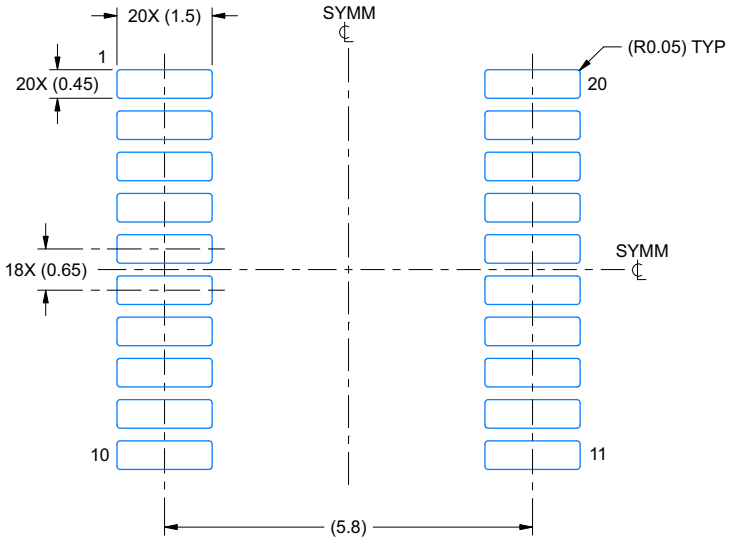
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

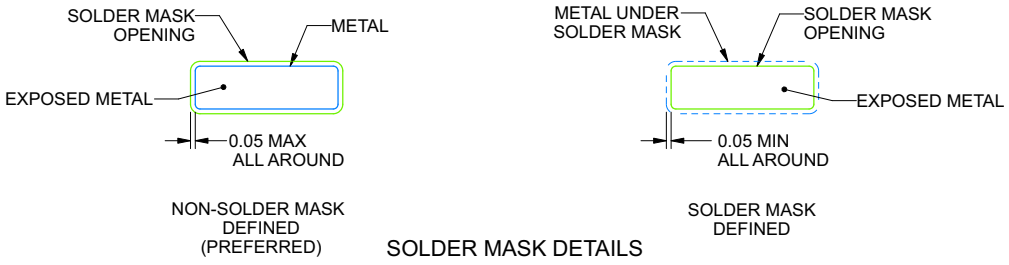
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

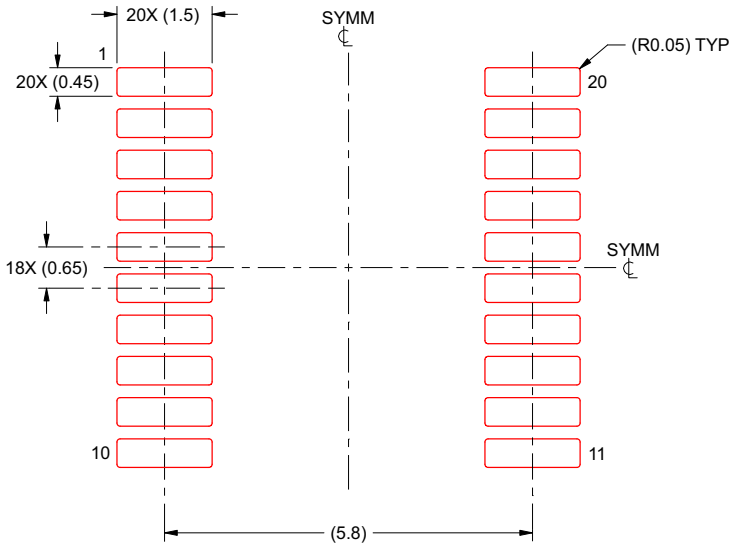
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A — **TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

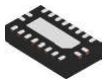
4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

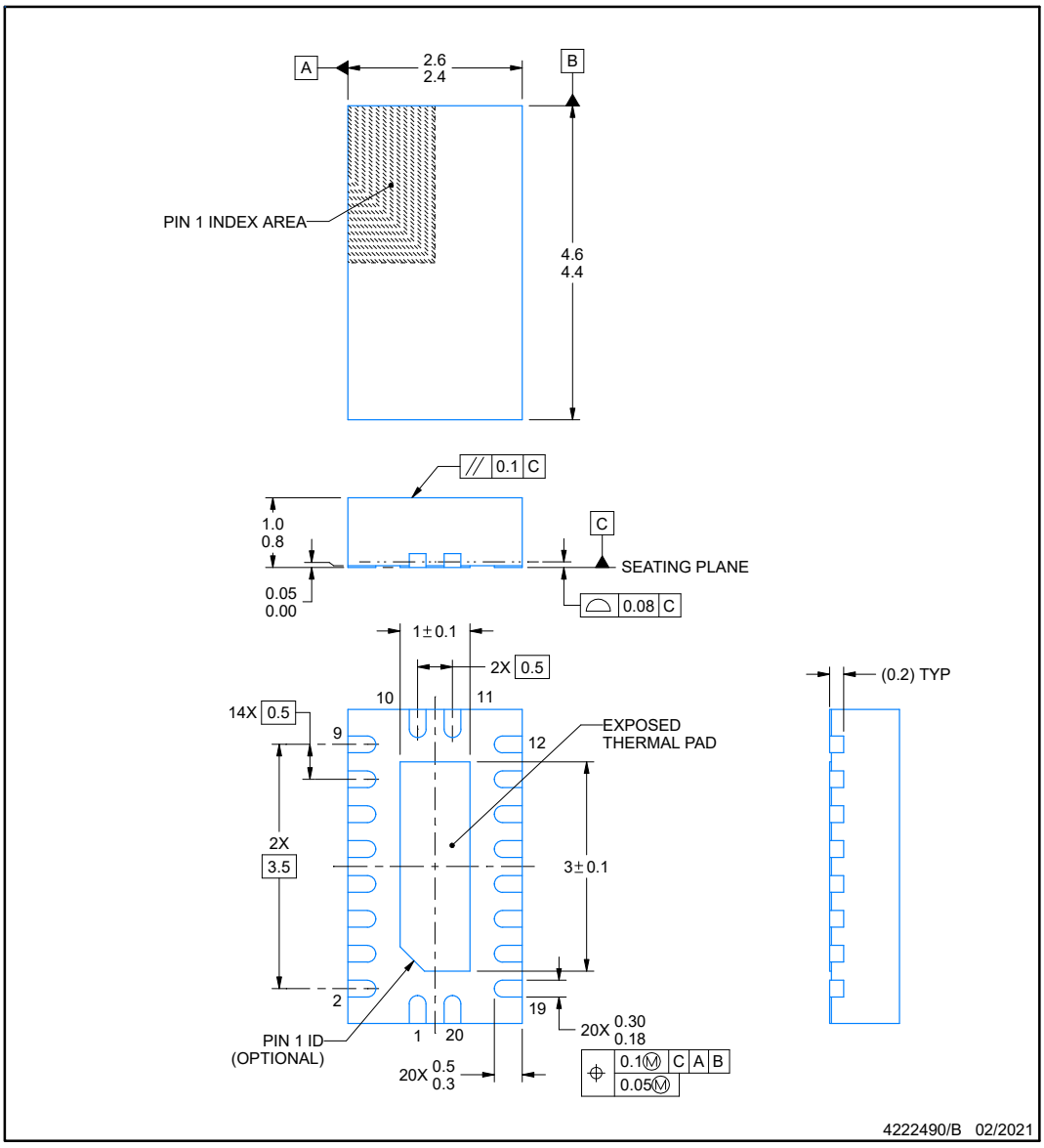
PACKAGE OUTLINE

RKS0020A



VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

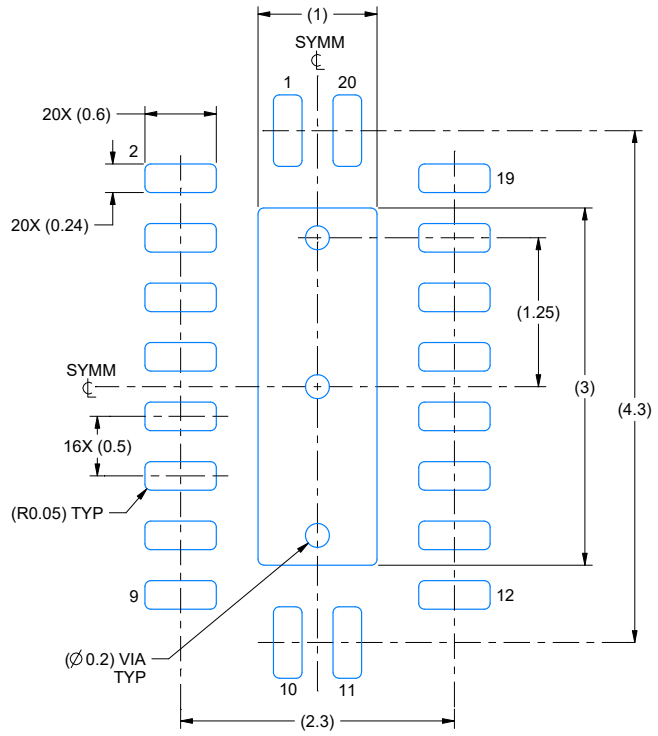
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

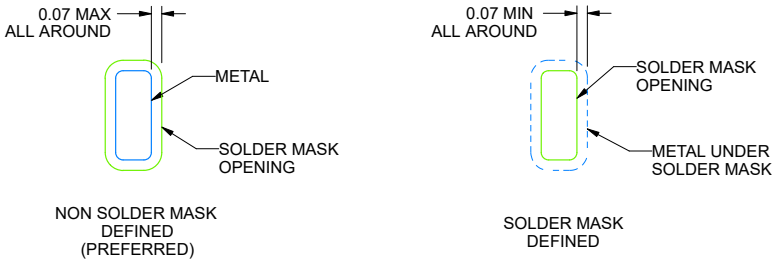
RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4222490/B 02/2021

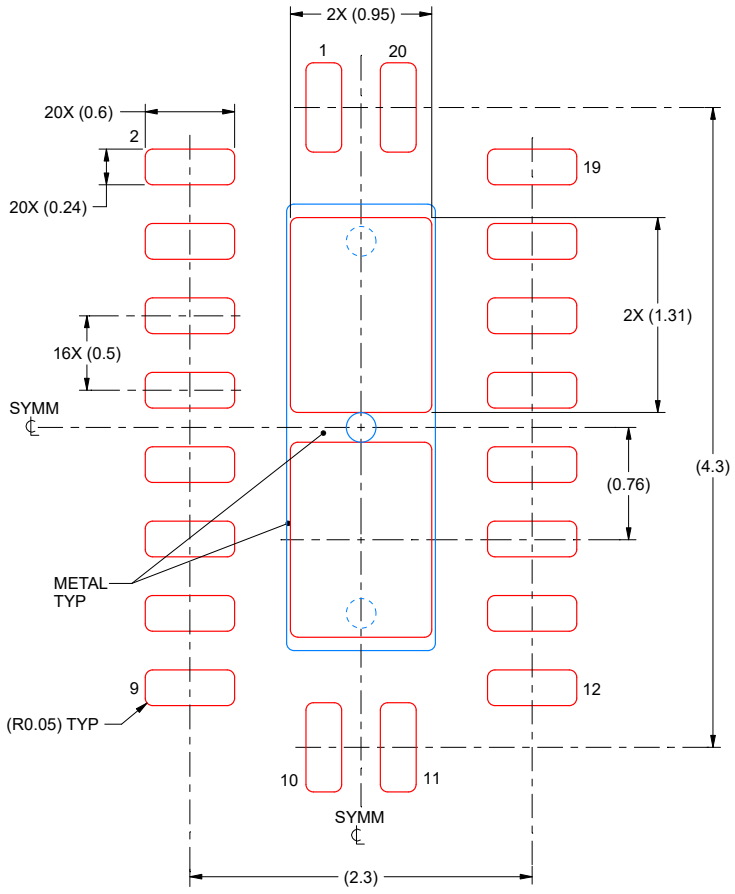
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

RKS0020A — **VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
83% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

4222490/B 02/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74CBTLV3245ARKSRQ1	Active	Production	VQFN (RKS) | 20	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	CL245AQ

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF SN74CBTLV3245A-Q1 :

- Catalog : SN74CBTLV3245A

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

GENERIC PACKAGE VIEW

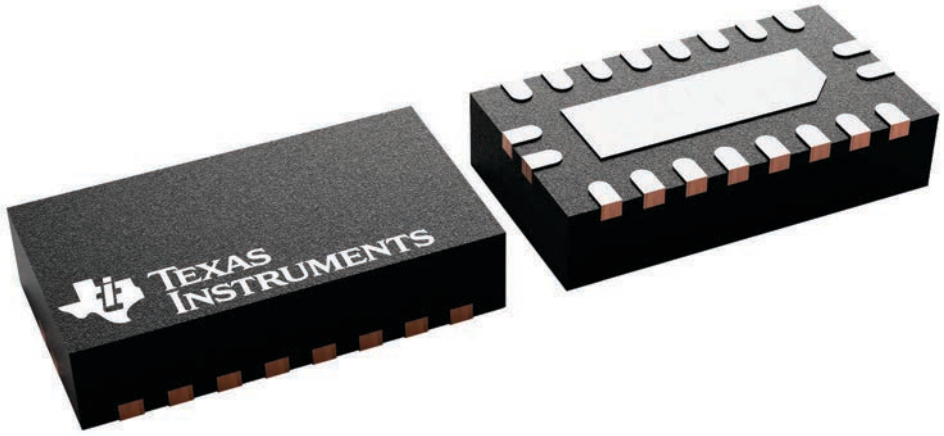
RKS 20

VQFN - 1 mm max height

2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



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Last updated 10/2025